



# Sierra Components, Inc.

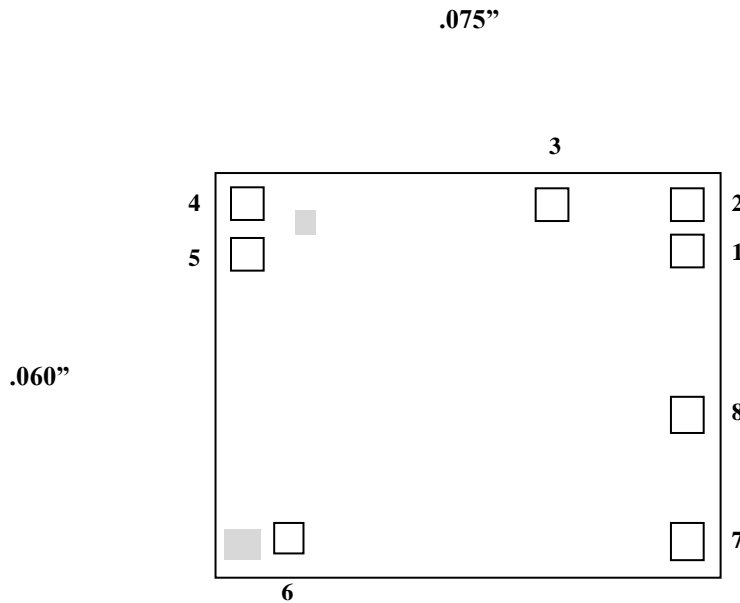
2222 Park Place • Suite 3E • Minden, Nevada 89423

Phone: 775.783.4940 Fax: 775.783.4947

Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.

### PAD FUNCTIONS

- 1 BAL/COMP-1
- 2 INPUT -
- 3 INPUT +
- 4 V -
- 5 BAL/COMP-3
- 6 OUTPUT
- 7 V +
- 8 COMP-2



**Top Material: Al**  
**Backside Material: Si**  
**Bond Pad Size: .004" min.**  
**Backside Potential: V-**  
**Mask Ref:**

**APPROVED BY: DK**

**DIE SIZE .060" X .075"**

**DATE: 8/20/20**

**MFG: TI / NATIONAL**

**THICKNESS .014"**

**P/N: LM318**